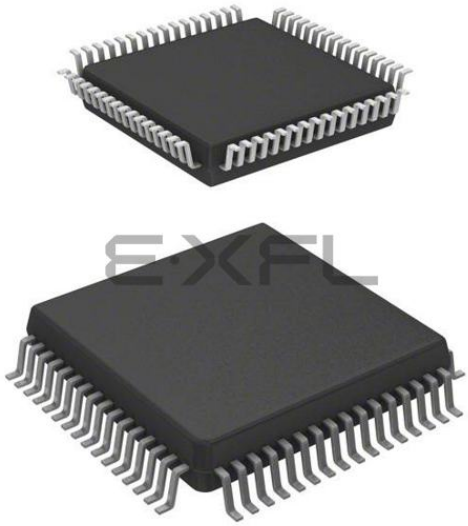

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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	H8/300H
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, SCI, SSU
Peripherals	LVD, POR, PWM, WDT
Number of I/O	45
Program Memory Size	56KB (56K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	3K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 75°C (TA)
Mounting Type	Surface Mount
Package / Case	64-BQFP
Supplier Device Package	64-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/df36037ghv

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Section 2 CPU

This LSI has an H8/300H CPU with an internal 32-bit architecture that is upward-compatible with the H8/300CPU, and supports only normal mode, which has a 64-kbyte address space.

- Upward-compatible with H8/300 CPUs
  - Can execute H8/300 CPUs object programs
  - Additional eight 16-bit extended registers
  - 32-bit transfer and arithmetic and logic instructions are added
  - Signed multiply and divide instructions are added.
- General-register architecture
  - Sixteen 16-bit general registers also usable as sixteen 8-bit registers and eight 16-bit registers, or eight 32-bit registers
- Sixty-two basic instructions
  - 8/16/32-bit data transfer and arithmetic and logic instructions
  - Multiply and divide instructions
  - Powerful bit-manipulation instructions
- Eight addressing modes
  - Register direct [Rn]
  - Register indirect [@ERn]
  - Register indirect with displacement [@(d:16,ERn) or @(d:24,ERn)]
  - Register indirect with post-increment or pre-decrement [@ERn+ or @–ERn]
  - Absolute address [@aa:8, @aa:16, @aa:24]
  - Immediate [#xx:8, #xx:16, or #xx:32]
  - Program-counter relative [@(d:8,PC) or @(d:16,PC)]
  - Memory indirect [@@aa:8]
- 64-kbyte address space
- High-speed operation
  - All frequently-used instructions execute in one or two states
  - 8/16/32-bit register-register add/subtract : 2 states
  - 8 × 8-bit register-register multiply : 14 states
  - 16 ÷ 8-bit register-register divide : 14 states
  - 16 × 16-bit register-register multiply : 22 states
  - 32 ÷ 16-bit register-register divide : 22 states

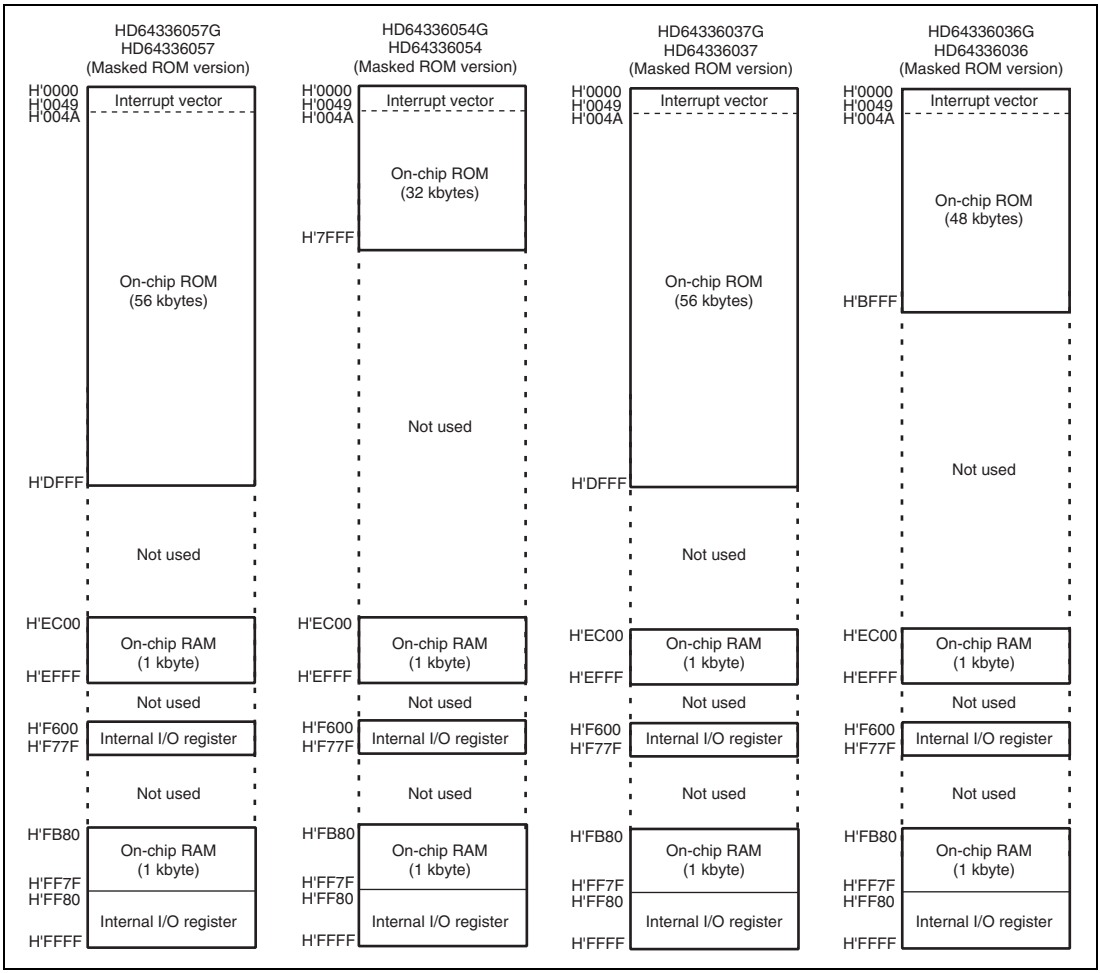

Figure 2.1 Memory Map (2)

2.4.2 Basic Instruction Formats

H8/300H CPU instructions consist of 2-byte (1-word) units. An instruction consists of an operation field (op), a register field (r), an effective address extension (EA), and a condition field (cc).

Figure 2.7 shows examples of instruction formats.

- Operation Field

  Indicates the function of the instruction, the addressing mode, and the operation to be carried out on the operand. The operation field always includes the first four bits of the instruction. Some instructions have two operation fields.
- Register Field

  Specifies a general register. Address registers are specified by 3 bits, and data registers by 3 bits or 4 bits. Some instructions have two register fields. Some have no register field.
- Effective Address Extension

  8, 16, or 32 bits specifying immediate data, an absolute address, or a displacement. A24-bit address or displacement is treated as a 32-bit data in which the first 8 bits are 0 (H'00).
- Condition Field

  Specifies the branching condition of Bcc instructions.

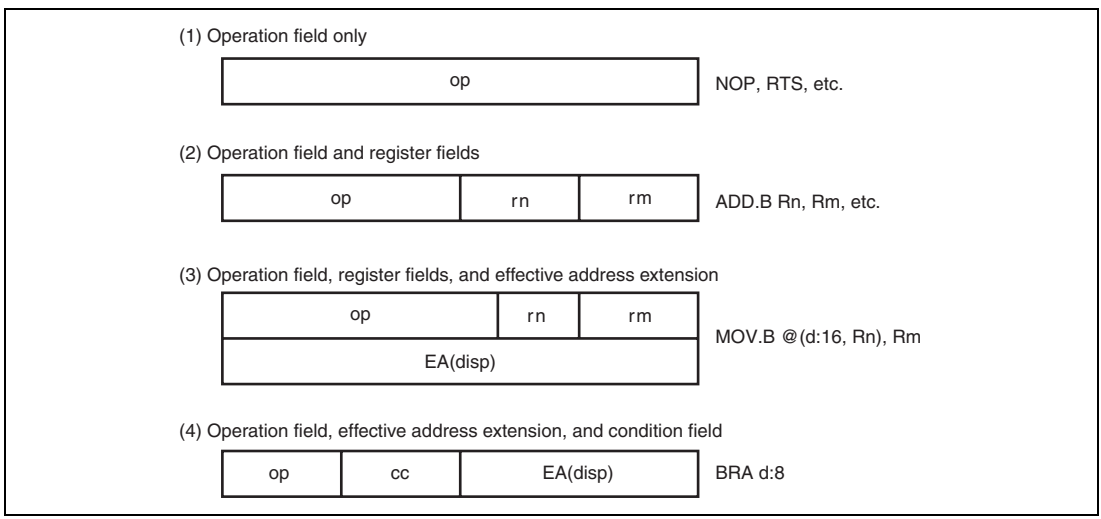

Figure 2.7 Instruction Formats

Section 3 Exception Handling

Exception handling may be caused by a reset, a trap instruction (TRAPA), or interrupts.

- Reset

  A reset has the highest exception priority. Exception handling starts as soon as the reset is cleared by the $\overline{\text{RES}}$ pin. The chip is also reset when the watchdog timer overflows, and exception handling starts. Exception handling is the same as exception handling by the $\overline{\text{RES}}$ pin.
- Trap Instruction

  Exception handling starts when a trap instruction (TRAPA) is executed. The TRAPA instruction generates a vector address corresponding to a vector number from 0 to 3, as specified in the instruction code. Exception handling can be executed at all times in the program execution state, regardless of the setting of the I bit in CCR.
- Interrupts

  External interrupts other than NMI and internal interrupts other than address break are masked by the I bit in CCR, and kept masked while the I bit is set to 1. Exception handling starts when the current instruction or exception handling ends, if an interrupt request has been issued.

- P22/TXD pin

Register	PMR1	PCR2	
Bit Name	**TXD**	**PCR22**	**Pin Function**
Setting Value	0	0	P22 input pin
		1	P22 output pin
	1	X	TXD output pin

[Legend]
X: Don't care.

- P21/RXD pin

Register	SCR3	PCR2	
Bit Name	**RE**	**PCR21**	**Pin Function**
Setting Value	0	0	P21 input pin
		1	P21 output pin
	1	X	RXD input pin

[Legend]
X: Don't care.

- P20/SCK3 pin

Register	SCR3		SMR	PCR2	
Bit Name	**CKE1**	**CKE0**	**COM**	**PCR20**	**Pin Function**
Setting Value	0	0	0	0	P20 input pin
				1	P20 output pin
	0	0	1	X	SCK3 output pin
	0	1	X	X	SCK3 output pin
	1	X	X	X	SCK3 input pin

[Legend]
X: Don't care.

- P52/$\overline{\text{WKP2}}$ pin

Register	PMR5	PCR5	
Bit Name	**WKP2**	**PCR52**	**Pin Function**
Setting Value	0	0	P52 input pin
		1	P52 output pin
	1	X	$\overline{\text{WKP2}}$ input pin

[Legend]
X: Don't care.

- P51/$\overline{\text{WKP1}}$ pin

Register	PMR5	PCR5	
Bit Name	**WKP1**	**PCR51**	**Pin Function**
Setting Value	0	0	P51 input pin
		1	P51 output pin
	1	X	$\overline{\text{WKP1}}$ input pin

[Legend]
X: Don't care.

- P50/$\overline{\text{WKP0}}$ pin

Register	PMR5	PCR5	
Bit Name	**WKP0**	**PCR50**	**Pin Function**
Setting Value	0	0	P50 input pin
		1	P50 output pin
	1	X	$\overline{\text{WKP0}}$ input pin

[Legend]
X: Don't care.

9.5.1 Port Control Register 7 (PCR7)

PCR7 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 7.

Bit	Bit Name	Initial Value	R/W	Description
7	—	—	—	When each of the port 7 pins P76 to P74 and P72 to P70 functions as a general I/O port, setting a PCR7 bit to 1 makes the corresponding pin an output port, while clearing the bit to 0 makes the pin an input port. Bits 7 and 3 are reserved bits.
6	PCR76	0	W	
5	PCR75	0	W	
4	PCR74	0	W	
3	—	—	—	
2	PCR72	0	W	
1	PCR71	0	W	
0	PCR70	0	W	

9.5.2 Port Data Register 7 (PDR7)

PDR7 is a general I/O port data register of port 7.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Stores output data for port 7 pins.
6	P76	0	R/W	If PDR7 is read while PCR7 bits are set to 1, the value stored in PDR7 are read. If PDR7 is read while PCR7 bits are cleared to 0, the pin states are read regardless of the value stored in PDR7. Bits 7 and 3 are reserved bits. These bits are always read as 1.
5	P75	0	R/W	
4	P74	0	R/W	
3	—	1	—	
2	P72	0	R/W	
1	P71	0	R/W	
0	P70	0	R/W	

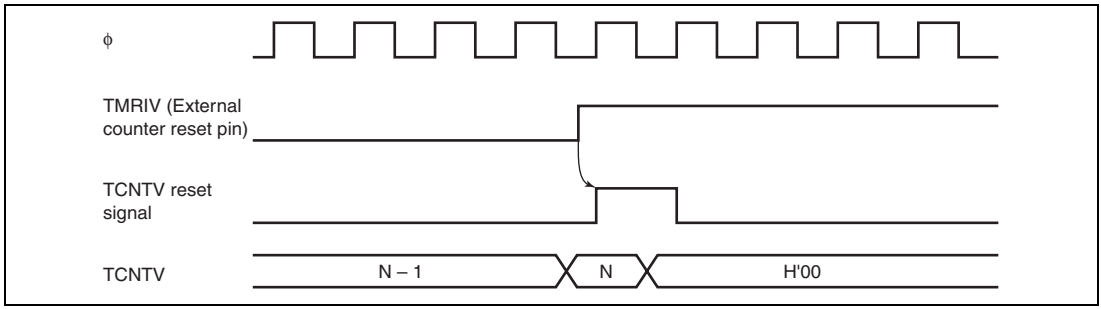

Figure 11.8 Clear Timing by TMRIV Input

11.5 Timer V Application Examples

11.5.1 Pulse Output with Arbitrary Duty Cycle

Figure 11.9 shows an example of output of pulses with an arbitrary duty cycle.

1. Set bits CCLR1 and CCLR0 in TCRV0 so that TCNTV will be cleared by compare match with TCORA.
2. Set bits OS3 to OS0 in TCSRV so that the output will go to 1 at compare match with TCORA and to 0 at compare match with TCORB.
3. Set bits CKS2 to CKS0 in TCRV0 and bit ICKS0 in TCRV1 to select the desired clock source.
4. With these settings, a waveform is output without further software intervention, with a period determined by TCORA and a pulse width determined by TCORB.

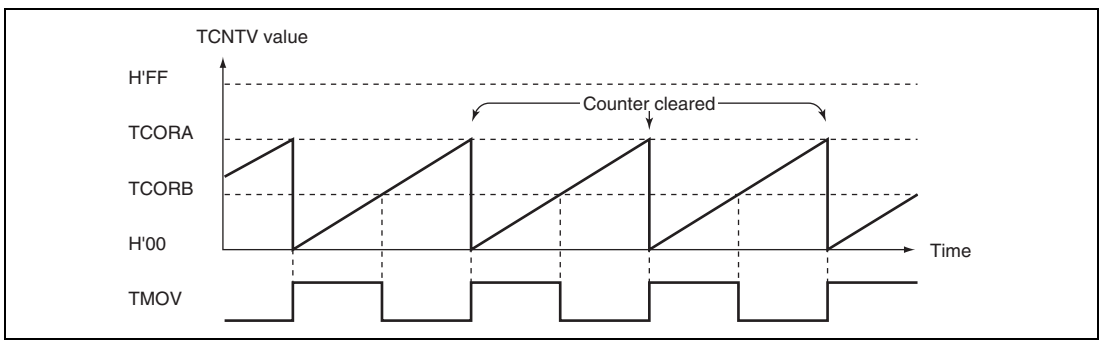

Figure 11.9 Pulse Output Example

- Eleven interrupt sources
  - — Four compare match/input capture interrupts and an overflow interrupt are available for each channel. An underflow interrupt can be set for channel 1.

Table 12.1 Timer Z Functions

Item		Channel 0	Channel 1
Count clock		Internal clocks: φ, φ/2, φ/4, φ/8 External clock: FTIOA0 (TCLK)	
General registers (output compare/input capture registers)		GRA_0, GRB_0, GRC_0, GRD_0	GRA_1, GRB_1, GRC_1, GRD_1
Buffer register		GRC_0, GRD_0	GRC_1, GRD_1
I/O pins		FTIOA0, FTIOB0, FTIOC0, FTIOD0	FTIOA1, FTIOB1, FTIOC1, FTIOD1
Counter clearing function		Compare match/input capture of GRA_0, GRB_0, GRC_0, or GRD_0	Compare match/input capture of GRA_1, GRB_1, GRC_1, or GRD_1
Compare match output	0 output	Yes	Yes
	1 output	Yes	Yes
	output	Yes	Yes
Input capture function		Yes	Yes
Synchronous operation		Yes	Yes
PWM mode		Yes	Yes
Reset synchronous PWM mode		Yes	Yes
Complementary PWM mode		Yes	Yes
Buffer function		Yes	Yes
Interrupt sources		Compare match/input capture A0 to D0 Overflow	Compare match/input capture A1 to D1 Overflow Underflow

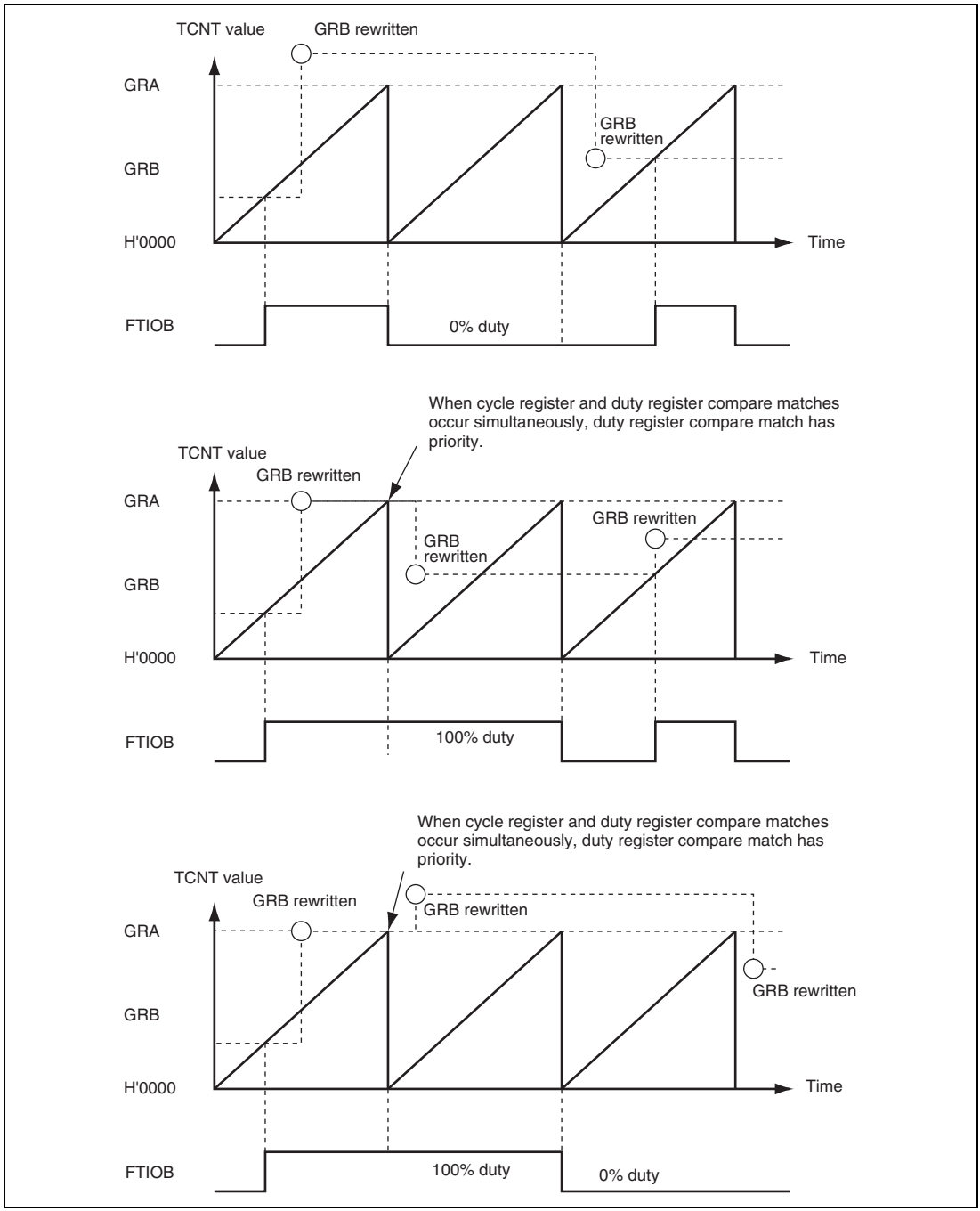

Figure 12.25 Example of PWM Mode Operation (4)

14.3.7 Serial Status Register (SSR)

SSR is a register containing status flags of the SCI3 and multiprocessor bits for transfer. 1 cannot be written to flags TDRE, RDRF, OER, PER, and FER; they can only be cleared.

Bit	Bit Name	Initial Value	R/W	Description
7	TDRE	1	R/W	Transmit Data Register Empty Indicates whether TDR contains transmit data. [Setting conditions] • When the TE bit in SCR3 is 0 • When data is transferred from TDR to TSR [Clearing conditions] • When 0 is written to TDRE after reading TDRE = 1 • When the transmit data is written to TDR
6	RDRF	0	R/W	Receive Data Register Full Indicates that the received data is stored in RDR. [Setting condition] • When serial reception ends normally and receive data is transferred from RSR to RDR [Clearing conditions] • When 0 is written to RDRF after reading RDRF = 1 • When data is read from RDR
5	OER	0	R/W	Overrun Error [Setting condition] • When an overrun error occurs in reception [Clearing condition] • When 0 is written to OER after reading OER = 1
4	FER	0	R/W	Framing Error [Setting condition] • When a framing error occurs in reception [Clearing condition] • When 0 is written to FER after reading FER = 1

	Operating Frequency ϕ (MHz)					
	18			20		
Bit Rate (bit/s)	n	N	Error (%)	n	N	Error (%)
110	3	79	–0.12	3	88	–0.25
150	2	233	0.14	3	64	0.14
300	2	114	0.14	2	129	0.14
600	1	233	0.14	2	64	0.14
1200	1	114	0.14	1	129	0.14
2400	0	233	0.14	1	64	0.14
4800	0	114	0.14	0	129	0.14
9600	0	58	–0.96	0	64	0.14
19200	0	28	1.02	0	32	–1.36
31250	0	17	0.00	0	19	0.00
38400	0	14	–2.34	0	15	1.73

[Legend]

—: A setting is available but error occurs.

Table 14.4 Maximum Bit Rate for Each Frequency (Asynchronous Mode)

ϕ (MHz)	Maximum Bit Rate (bit/s)	n	N	ϕ (MHz)	Maximum Bit Rate (bit/s)	n	N
2	62500	0	0	8	250000	0	0
2.097152	65536	0	0	9.8304	307200	0	0
2.4576	76800	0	0	10	312500	0	0
3	93750	0	0	12	375000	0	0
3.6864	115200	0	0	12.288	384000	0	0
4	125000	0	0	14	437500	0	0
4.9152	153600	0	0	14.7456	460800	0	0
5	156250	0	0	14	500000	0	0
6	187500	0	0	17.2032	537600	0	0
6.144	192000	0	0	18	562500	0	0
7.3728	230400	0	0	20	625000	0	0

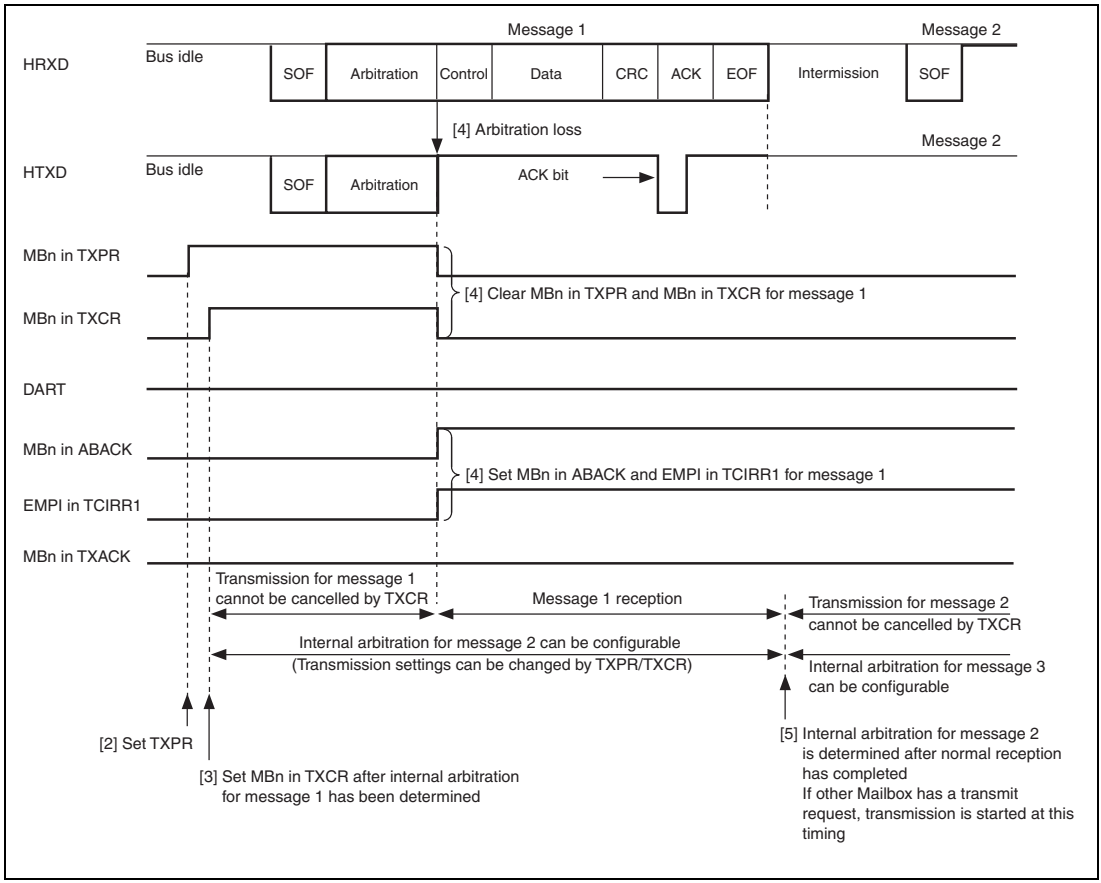

Figure 15.9 Internal Arbitration at Reception Caused by CAN Bus Arbitration Loss (MBn in TXCR = 1)

16.3.1 SS Control Register H (SSCRH)

SSCRH is a register that selects a master or a slave device, enables bidirectional mode, selects open-drain output of the serial data output pin, selects an output value of the serial data output pin, selects the SSCK pin, and selects the $\overline{SCS}$ pin.

Bit	Bit Name	Initial Value	R/W	Description
7	MSS	0	R/W	Master/Slave Device Select Selects whether this module is used as a master device or a slave device. When this module is used as a master device, transfer clock is output from the SSCK pin. When the CE bit in SSSR is set, this bit is automatically cleared. 0: Operates as a slave device 1: Operates as a master device
6	BIDE	0	R/W	Bidirectional Mode Enable Selects whether the serial data input pin and the output pin are both used or only one pin is used. For details, refer to section 16.4.3, Relationship between Data Input/Output Pin and Shift Register. When the SSUMS bit in SSCRL is 0, this setting is invalid. 0: Normal mode. Communication is performed by using two pins. 1: Bidirectional mode. Communication is performed by using only one pin.
5	SOOS	0	R/W	Serial Data Open-Drain Output Select Selects whether the serial data output pin is CMOS output or NMOS open-drain output. The serial data output pin is changed according to the register setting value. For details, refer to section 16.4.3, Relationship between Data Input/Output Pin and Shift Register. 0: CMOS output 1: NMOS open-drain output

Item	Symbol	Applicable Pins	Test Condition	Values Min.	Typ.	Max.	Unit	Notes
Pull-up MOS current	$-I_p$	P10 to P12, P14 to P17,P50 to P55	V_{CC} = 5.0 V, V_{IN} = 0.0 V	50.0	—	300.0	µA	
			V_{CC} = 3.0 V, V_{IN} = 0.0 V	—	60.0	—		Reference value
Input capacitance	C_{in}	All input pins except power supply pins	f = 1 MHz, V_{IN} = 0.0 V, T_a = 25°C	—	—	15.0	pF	
Active mode supply current	I_{OPE1}	V_{CC}	Active mode 1 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	25.0	35.0	mA	*3
			Active mode 1 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	10.0	—		*3 Reference value
	I_{OPE2}	V_{CC}	Active mode 2 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	1.2	3.0	mA	*3
			Active mode 2 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	0.8	—		*3 Reference value
Sleep mode supply current	I_{SLEEP1}	V_{CC}	Sleep mode 1 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	14.0	22.5	mA	*3
			Sleep mode 1 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	6.3	—		*3 Reference value
	I_{SLEEP2}	V_{CC}	Sleep mode 2 V_{CC} = 5.0 V, f_{OSC} = 20 MHz	—	1.0	2.7	mA	*3
			Sleep mode 2 V_{CC} = 3.0 V, f_{OSC} = 10 MHz	—	0.7	—		*3 Reference value
Subactive mode supply current	I_{SUB}	V_{CC}	V_{CC} = 5.0 V ($\phi_{SUB} = \phi_W/2$)	—	60.0	100.0	µA	*3
			V_{CC} = 5.0 V ($\phi_{SUB} = \phi_W/8$)	—	46.0	—		*3 Reference value
Subsleep mode supply current	I_{SUBSP}	V_{CC}	V_{CC} = 5.0 V ($\phi_{SUB} = \phi_W/2$)	—	50.0	80.0	µA	*3

2. Arithmetic Instructions

Mnemonic		Operand Size	Addressing Mode and Instruction Length (bytes)									Operation	Condition Code						No. of States*1	
			#xx	Rn	@ERn	@(d, ERn)	@–ERn/@ERn+	@aa	@(d, PC)	@@aa	—		I	H	N	Z	V	C	Normal	Advanced
ADD	ADD.B #xx:8, Rd	B	2									Rd8+#xx:8 → Rd8	—	↕	↕	↕	↕	↕	2	
	ADD.B Rs, Rd	B		2								Rd8+Rs8 → Rd8	—	↕	↕	↕	↕	↕	2	
	ADD.W #xx:16, Rd	W	4									Rd16+#xx:16 → Rd16	—	(1)	↕	↕	↕	↕	4	
	ADD.W Rs, Rd	W		2								Rd16+Rs16 → Rd16	—	(1)	↕	↕	↕	↕	2	
	ADD.L #xx:32, ERd	L	6									ERd32+#xx:32 → ERd32	—	(2)	↕	↕	↕	↕	6	
	ADD.L ERs, ERd	L		2								ERd32+ERs32 → ERd32	—	(2)	↕	↕	↕	↕	2	
ADDX	ADDX.B #xx:8, Rd	B	2									Rd8+#xx:8 +C → Rd8	—	↕	↕	(3)	↕	↕	2	
	ADDX.B Rs, Rd	B		2								Rd8+Rs8 +C → Rd8	—	↕	↕	(3)	↕	↕	2	
ADDS	ADDS.L #1, ERd	L		2								ERd32+1 → ERd32	—	—	—	—	—	—	2	
	ADDS.L #2, ERd	L		2								ERd32+2 → ERd32	—	—	—	—	—	—	2	
	ADDS.L #4, ERd	L		2								ERd32+4 → ERd32	—	—	—	—	—	—	2	
INC	INC.B Rd	B		2								Rd8+1 → Rd8	—	—	↕	↕	↕	—	2	
	INC.W #1, Rd	W		2								Rd16+1 → Rd16	—	—	↕	↕	↕	—	2	
	INC.W #2, Rd	W		2								Rd16+2 → Rd16	—	—	↕	↕	↕	—	2	
	INC.L #1, ERd	L		2								ERd32+1 → ERd32	—	—	↕	↕	↕	—	2	
	INC.L #2, ERd	L		2								ERd32+2 → ERd32	—	—	↕	↕	↕	—	2	
DAA	DAA Rd	B		2								Rd8 decimal adjust → Rd8	—	*	↕	↕	*	↕	2	
SUB	SUB.B Rs, Rd	B		2								Rd8–Rs8 → Rd8	—	↕	↕	↕	↕	↕	2	
	SUB.W #xx:16, Rd	W	4									Rd16–#xx:16 → Rd16	—	(1)	↕	↕	↕	↕	4	
	SUB.W Rs, Rd	W		2								Rd16–Rs16 → Rd16	—	(1)	↕	↕	↕	↕	2	
	SUB.L #xx:32, ERd	L	6									ERd32–#xx:32 → ERd32	—	(2)	↕	↕	↕	↕	6	
	SUB.L ERs, ERd	L		2								ERd32–ERs32 → ERd32	—	(2)	↕	↕	↕	↕	2	
SUBX	SUBX.B #xx:8, Rd	B	2									Rd8–#xx:8–C → Rd8	—	↕	↕	(3)	↕	↕	2	
	SUBX.B Rs, Rd	B		2								Rd8–Rs8–C → Rd8	—	↕	↕	(3)	↕	↕	2	
SUBS	SUBS.L #1, ERd	L		2								ERd32–1 → ERd32	—	—	—	—	—	—	2	
	SUBS.L #2, ERd	L		2								ERd32–2 → ERd32	—	—	—	—	—	—	2	
	SUBS.L #4, ERd	L		2								ERd32–4 → ERd32	—	—	—	—	—	—	2	
DEC	DEC.B Rd	B		2								Rd8–1 → Rd8	—	—	↕	↕	↕	—	2	
	DEC.W #1, Rd	W		2								Rd16–1 → Rd16	—	—	↕	↕	↕	—	2	
	DEC.W #2, Rd	W		2								Rd16–2 → Rd16	—	—	↕	↕	↕	—	2	

Table A.2 Operation Code Map (2)

Instruction code:

1st byte	2nd byte
AH AL	BH BL

AH AL \ BH	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
01	MOV				LDC/STC				SLEEP				Table A.2 (3)	Table A.2 (3)		Table A.2 (3)
0A	INC												ADD			
0B	ADDS					INC		INC	ADDS					INC		INC
0F	DAA												MOV			
10	SHLL			SHLL					SHAL			SHAL				
11	SHLR			SHLR					SHAR			SHAR				
12	ROTXL			ROTXL					ROTL			ROTL				
13	ROTXR			ROTXR					ROTR			ROTR				
17	NOT			NOT		EXTU		EXTU	NEG			NEG		EXTS		EXTS
1A	DEC												SUB			
1B	SUBS					DEC		DEC	SUB					DEC		DEC
1F	DAS												CMP			
58	BRA	BRN	BHI	BLS	BCC	BCS	BNE	BEQ	BVC	BVS	BPL	BMI	BGE	BLT	BGT	BLE
79	MOV	ADD	CMP	SUB	OR	XOR	AND									
7A	MOV	ADD	CMP	SUB	OR	XOR	AND									

Renesas Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

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Renesas Technology America, Inc.
450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.
Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510